

GC40002A IST COUPON INFORMATION – Buried (Core) Vias

(With capacitance holes)

This package contains design files for a generic Interconnect Stress Test (IST) Test Coupon containing **Plated Through Hole and Buried (Core) Via Technologies** on a 5.0" (126.9mm) X 0.6" (15.2mm) coupon with a total thickness up to .125" (3.2mm) and limited to a minimum of 6 layers. The core vias run between layers 2 and N-1 only. This coupon is designed on a small grid, .040" (1mm). The maximum hole/pad size is .015" (.38mm) and pad size is .028" (.71mm) for both power and sense circuits; decreasing these feature sizes will not affect the coupon functionality but increasing these feature sizes may result in shorts or excessively small clearances. Instructions on how to create a custom IST coupon for a specific product are included.

If a design with internal buried vias is needed, please refer to GBu4001A. This can accommodate buried vias anywhere between layer 4 and n-3.

For further information and general inquires on IST technology visit our web site at: www.pwbcorp.com

